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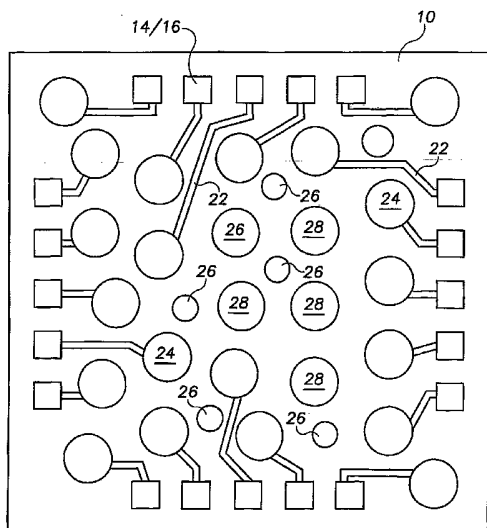
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For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: POLYMER REDISTRIBUTION OF FLIP CHIP BOND PADS



(57) Abstract: An electrical interconnection structure for a flip chip is produced for a flip chip having a plurality of chip bond pads in electrical connection with an electronic circuit, where the chip bond pads are provided on a first face of the flip chip. Electrically-conductive polymer bump bond pads are formed on the first face of the flip chip in an arrangement selected for electrical interconnection of the flip chip with a substrate. A plurality of electrically-conductive polymer redistribution traces are formed on the first face of the flip chip, each trace electrically connecting a chip bond pad to a bump bond pad. The electrically-conductive polymer bump bond pads and redistribution traces can be provided together as a common patterned electrically-conductive polymer layer by, e.g., stencilling or screen printing, to enable in one geometrically defined layer both redistribution traces and interconnection bump bond pads. Historically, redistribution traces and bump bond pads have been provided as a metal layer, e.g., an aluminium layer, formed by, e.g., a sputtering or other metal deposition process, and geometrically defined by a separate photolithography technique. Employing an electrically-conductive polymer layer rather than a metal layer, the invention overcomes the limitations of a metal layer and expands the range of applications that are addressed by a flip chip bond pad redistribution configuration.

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INTERNATIONAL SEARCH REPORT

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PC/US 01/26436

A. CLASSIFICATION OF SUBJECT MATTER
IPC 7 H01L23/485

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

IPC 7 H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal, WPI Data, PAJ

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 6 084 303 A (THEVENOT BENOIT ET AL) 4 July 2000 (2000-07-04) abstract; figures 1-8 column 2, line 27 - line 45 column 2, line 61 -column 4, line 10	1,2,5,6, 13-18, 20,21,30
A	claims 1-3	3,4,7,8, 10-12, 22-26
X	US 5 147 210 A (PATTERSON TIMOTHY P ET AL) 15 September 1992 (1992-09-15) abstract; figures 4,9,10 column 3, line 42 -column 3, line 68 column 5, line 21 -column 7, line 27	1-4,15, 20-23
A	claims 1-3,7,8,10-12,14	10-14,30
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Patent family members are listed in annex.

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C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

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